



Integrated Device Technology, Inc.

3.3V CMOS 16-BIT REGISTER

**IDT74ALVCH16374
IDT74ALVCH162374
IDT74ALVC16374
ADVANCE INFORMATION**

FEATURES:

- **Common features:**
 - 0.5 MICRON CMOS Technology
 - **Typical tsk(o) (Output Skew) < 250ps**
 - ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
 - 25 mil pitch SSOP, 19.6 mil pitch TSSOP, and 15.7 mil pitch TVSOP packages
 - Extended commercial range of -40°C to +85°C
 - Vcc = 3.3V ±0.3V, Normal Range
 - Vcc = 2.7V to 3.6V, Extended Range
 - Vcc = 2.5V ±0.2V
 - CMOS power levels (0.4µW typ. static)
 - Rail-to-Rail output swing for increased noise margin
- **Features for ALVCH16374 and ALVC16374:**
 - High Drive Outputs: ±24mA
 - Suitable for heavy loads
- **Features for ALVCH162374:**
 - Light Balanced Output Driver: ±12mA
 - Minimal switching noise

DESCRIPTION:

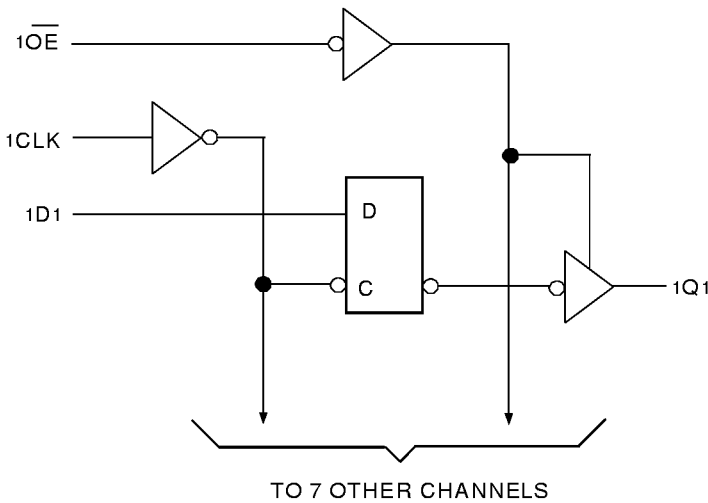
The ALVCH16374 16-bit edge-triggered D-type registers are built using advanced dual metal CMOS technology. These high-speed, low-power registers are ideal for use as buffer registers for data synchronization and storage. The Output Enable (xOE) and clock (xCLK) controls are organized to operate each device as two 8-bit registers or one 16-bit register with common clock. Flow-through organization of signal pins facilitates ease of layout. All inputs are designed with hysteresis for improved noise margin.

The ALVCH16x374 have "bus-hold" which retains the input's last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistor.

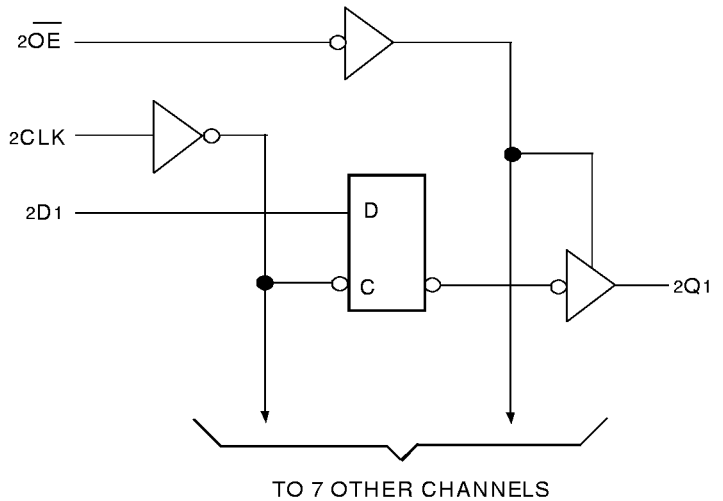
The ALVCH16374/ALVC16374 have been designed with a ±24mA output driver. These drivers are capable of driving a moderate to heavy load while maintaining speed performance.

The ALVCH162374 has series resistors in the device output structure which will significantly reduce line noise when used with light loads. This driver has been designed to drive ±12mA at the designated threshold levels.

FUNCTIONAL BLOCK DIAGRAM



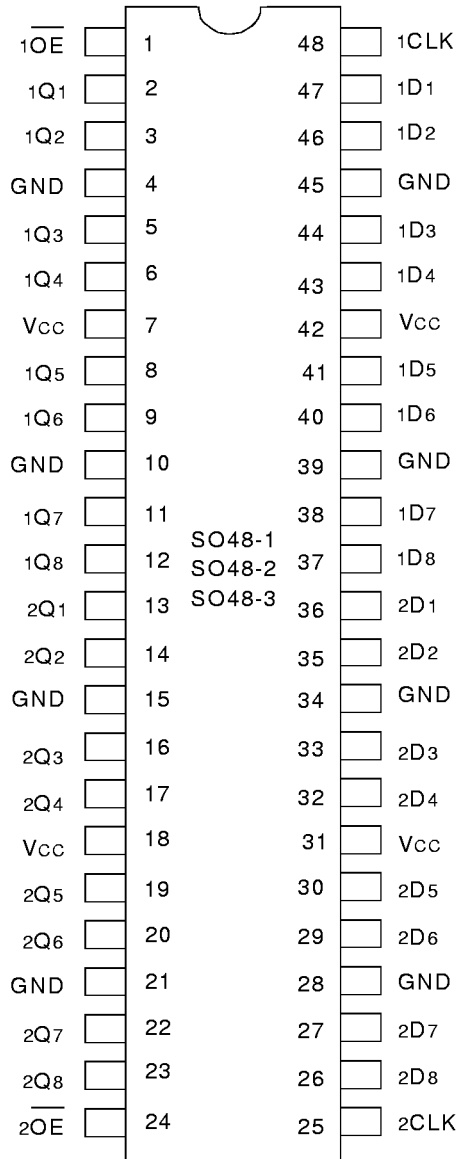
4218 drw 01



4218 drw 02

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PIN CONFIGURATIONS



SSOP/
TSSOP/TVSOP
TOP VIEW

4218 dw 03

PIN DESCRIPTION

Pin Names	Description
xDx	Data Inputs ⁽¹⁾
xCLK	Clock Inputs
xQx	3-State Outputs.
xOE	3-State Output Enable Input (Active LOW)

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NOTE:
1. On ALVCH these pins have "Bus-hold". All other pins are standard inputs outputs or I/Os. On ALVC no pins have "Bus-hold".

ABSOLUTE MAXIMUM RATING⁽¹⁾

Symbol	Description	Max.	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc +0.5	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	DC Output Current	-60 to +60	mA
I _{IK} I _{OK}	Continuous Clamp Current, V _I < 0 or V _O < 0	-50	mA
I _{CC} I _{SS}	Continuous Current through each Vcc or GND	±100	mA

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- NOTES:**
- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
 - Vcc terminals.
 - All terminals except Vcc.

CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	5.0	7.0	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	7.0	9.0	pF
C _{I/O}	I/O Port Capacitance	V _{IN} = 0V	7.0	9.0	pF

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- NOTE:**
1. As applicable to the device type.

FUNCTION TABLE⁽¹⁾

Function	Inputs			Outputs
	xDx	xCLK	xOE	xQx
Hi-Z	X	L	H	Z
	X	H	H	Z
Load Register	L	↑	L	L
	H	↑	L	H
	L	↑	H	Z
	H	↑	H	Z

4218 tbl 04

- NOTE:**
- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
Z = High-Impedance
↑ = LOW-to-HIGH Transition

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
V _{IH}	Input HIGH Voltage Level	V _{CC} = 2.3V to 2.7V		1.7	—	—	V
		V _{CC} = 2.7V to 3.6V		2	—	—	
V _{IL}	Input LOW Voltage Level	V _{CC} = 2.3V to 2.7 V		—	—	0.7	V
		V _{CC} = 2.7V to 3.6V		—	—	0.8	
I _{IH}	Input HIGH Current	V _{CC} = 3.6V	V _I = V _{CC}	—	—	±1	μA
I _{IL}	Input LOW Current	V _{CC} = 3.6V	V _I = GND	—	—	±1	
IOZH	High Impedance Output Current (3-State Output pins)	V _{CC} = 3.6V	V _O = V _{CC}	—	—	±1	μA
IOZL			V _O = GND	—	—	±1	μA
V _{IK}	Clamp Diode Voltage	V _{CC} = 2.3V, I _{IN} = -18mA		—	0.7	-1.2	V
V _H	Input Hysteresis	V _{CC} = 3.3V		—	100	—	mV
ICCL	Quiescent Power Supply Current	V _{CC} = 3.6V		—	0.1	40	μA
ICCH		V _{IN} = GND or V _{CC}					
IC CZ							

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BUS-HOLD CHARACTERISTICS FOR ALVCH16x374

Symbol	Parameter ⁽²⁾	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
I _{BHH}	Bus-Hold Input Sustain Current	V _{CC} = 3.0V	V _I = 2.0V	-75	—	—	μA
			V _I = 0.8V	75	—	—	
I _{BHL}	Bus-Hold Input Sustain Current	V _{CC} = 2.3V	V _I = 1.7V	-45	—	—	μA
			V _I = 0.7V	45	—	—	
I _{BHHO}	Bus-Hold Input Overdrive Current	V _{CC} = 3.6V	V _I = 0 to 3.6V	—	—	±500	μA
I _{BHLO}							

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NOTES:

1. Typical values are at V_{CC} = 3.3V, +25°C ambient.
2. Pins with Bus-hold are identified in the pin description.

OUTPUT DRIVE CHARACTERISTICS FOR ALVCH16374 AND ALVC16374

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
VOH	Output HIGH Voltage	VCC = 2.3V to 3.6V	IOH = -0.1mA	VCC-0.2	—	V
		VCC = 2.3V	IOH = -6mA	2	—	
		VCC = 2.3V	IOH = -12mA	1.7	—	
		VCC = 2.7V		2.2	—	
		VCC = 3.0V		2.4	—	
		VCC = 3.0V	IOH = -24mA	2	—	
VOL	Output LOW Voltage	VCC = 2.3V to 3.6V	IOL = 0.1mA	—	0.2	V
		VCC = 2.3V	IOL = 6mA	—	0.4	
			IOL = 12mA	—	0.7	
		VCC = 2.7V	IOL = 12mA	—	0.4	
		VCC = 3.0V	IOL = 24mA	—	0.55	

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OUTPUT DRIVE CHARACTERISTICS FOR ALVCH162374

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
VOH	Output HIGH Voltage	VCC = 2.3V to 3.6V	IOH = -0.1mA	VCC-0.2	—	V
		VCC = 2.3V	IOH = -4mA	1.9	—	
		VCC = 2.3V	IOH = -6mA	1.7	—	
		VCC = 2.7V	IOH = -8mA	2	—	
		VCC = 3.0V	IOH = -6mA	2.4	—	
		VCC = 3.0V	IOH = -12mA	2	—	
VOL	Output LOW Voltage	VCC = 2.3V to 3.6V	IOL = 0.1mA	—	0.2	V
		VCC = 2.3V	IOL = 4mA	—	0.4	
			IOL = 6mA	—	0.55	
		VCC = 2.7V	IOL = 8mA	—	0.6	
		VCC = 3.0V	IOL = 12mA	—	0.8	

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NOTE:

1. VIH and VIL must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate VCC range. TA = -40°C to +85°C.

SWITCHING CHARACTERISTICS FOR ALVCH16374 AND ALVC16374⁽¹⁾

Symbol	Parameter	V _{CC} = 2.5V ±0.2V		V _{CC} = 2.7V		V _{CC} = 3.3V ±0.3V		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
f _{MAX}	xCLK Frequency	0	150	0	150	0	150	MHz
t _{PLH} t _{PHL}	Propagation Delay xCLK to xQx	1	5.9	1	4.9	1	4.2	ns
t _{PZH} t _{PZL}	Output Enable Time	1	6.7	1	5.9	1	4.8	ns
t _{PHZ} t _{PLZ}	Output Disable Time	1.7	5.5	1	4.7	1.2	4.3	ns
t _{SU}	Set-up Time HIGH or LOW xDx to xCLK	2.1	—	2.2	—	1.9	—	ns
t _H	Hold Time HIGH or LOW xDx after xCLK	0.6	—	0.5	—	0.5	—	ns
t _w	xCLK Pulse Width HIGH or LOW	3.3	—	3.3	—	3.3	—	ns
t _{SK(o)}	Output Skew ⁽²⁾	0	500	0	500	0	500	ps

4218 tbl 09

SWITCHING CHARACTERISTICS FOR ALVCH162374⁽¹⁾

Symbol	Parameter	V _{CC} = 2.5V ±0.2V		V _{CC} = 2.7V		V _{CC} = 3.3V ±0.3V		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
f _{MAX}	xCLK Frequency	0		0		0		MHz
t _{PLH} t _{PHL}	Propagation Delay xCLK to xQx	1		1		1		ns
t _{PZH} t _{PZL}	Output Enable Time	1		1		1		ns
t _{PHZ} t _{PLZ}	Output Disable Time	1		1		1.2		ns
t _{SU}	Set-up Time HIGH or LOW xDx to xCLK		—		—		—	ns
t _H	Hold Time HIGH or LOW xDx after xCLK		—		—		—	ns
t _w	xCLK Pulse Width HIGH or LOW		—		—		—	ns
t _{SK(o)}	Output Skew ⁽²⁾	0	500	0	500	0	500	ps

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NOTES:

1. See test circuits and waveforms. T_A = -40°C to +85°C.
2. Skew between any two outputs of the same package switching in the same direction.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
ΔI_{CC}	Quiescent Power Supply Current TTL Standard Inputs HIGH	$V_{CC} = \text{Max.}$	$V_{IN} = V_{CC} - 0.6V^{(3)}$	—	2.0	30	μA
ΔI_{CC}	Quiescent Power Supply Current TTL Bus-hold Inputs HIGH	$V_{CC} = \text{Max.}$	$V_{IN} = V_{CC} - 0.6V^{(3)}$	—	162	325	μA
I_{CCD}	Dynamic Power Supply Current ^(4,5)	$V_{CC} = \text{Max.}$ Outputs Open $\overline{xOE} = \text{GND}$ 50% Duty Cycle One Input Toggling	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	50	75	$\mu A / \text{MHz}$
I_C	Total Power Supply Current ⁽⁶⁾	$V_{CC} = \text{Max.}$ Outputs Open $f_{CP} = 10\text{MHz}$ 50% Duty Cycle $\overline{xOE} = \text{GND}$ $f_i = 5\text{MHz}$ 50% Duty Cycle One Bit Toggling	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	0.5	0.8	mA
			$V_{IN} = V_{CC} - 0.6V$ $V_{IN} = \text{GND}$	—	0.5	0.8	
		$V_{CC} = \text{Max.}$ Outputs Open $f_{CP} = 10\text{MHz}$ 50% Duty Cycle $\overline{xOE} = \text{GND}$ $f_i = 2.5\text{MHz}$ 50% Duty Cycle Sixteen Bits Toggling	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	2.5	3.8	
			$V_{IN} = V_{CC} - 0.6V$ $V_{IN} = \text{GND}$	—	2.5	4.0	

NOTES:

- $V_{CC} (\text{max.}) = 3.6V$
- Typical values are at $V_{CC} = 3.3V$, $+25^\circ C$ ambient.
- Per TTL driven input; all other inputs at V_{CC} or GND .
- This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- $CPD = I_{CCD} / V_{CC}$
 $CPD = \text{Power Dissipation Capacitance}$
- $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
 $I_C = I_{CC} + \Delta I_{CC} D_{HNT} + I_{CCD} (f_{CP} N_{CP} / 2 + f_i N_i)$
 $I_{CC} = \text{Quiescent Current (} I_{CCL}, I_{CCH} \text{ and } I_{CCZ} \text{)}$
 $\Delta I_{CC} = \text{Power Supply Current for a TTL High Input}$
 $D_H = \text{Duty Cycle for TTL Inputs High}$
 $N_T = \text{Number of TTL Inputs at } D_H$
 $I_{CCD} = \text{Dynamic Current Caused by an Input Transition Pair (HLH or LHL)}$
 $f_{CP} = \text{Clock Frequency for Register Devices (Zero for Non-Register Devices)}$
 $N_{CP} = \text{Number of Clock Inputs at } f_{CP}$
 $f_i = \text{Input Frequency}$
 $N_i = \text{Number of Inputs at } f_i$

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TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

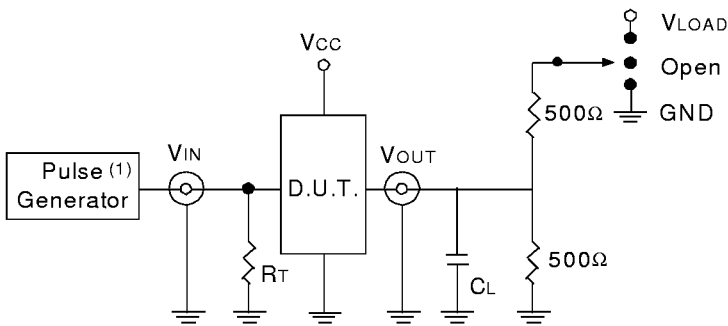
Symbol	Vcc = 3.3V ±0.3V	Vcc = 2.7V	Vcc = 2.5V±0.2V	Unit
V _{LOAD}	6	6	4.6	V
V _{IH}	2.7	2.7	2.3	V
V _T	1.5	1.5	V _{CC} /2	V
V _{LZ}	300	300	150	mV
V _{HZ}	300	300	150	mV
C _L	50	50	30	pF

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DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.
R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

TEST CIRCUITS FOR ALL OUTPUTS

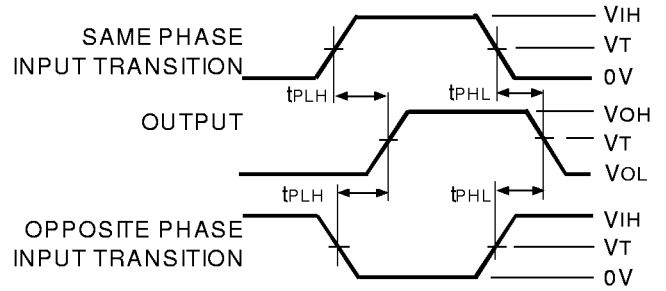


4218 drw 04

NOTE:

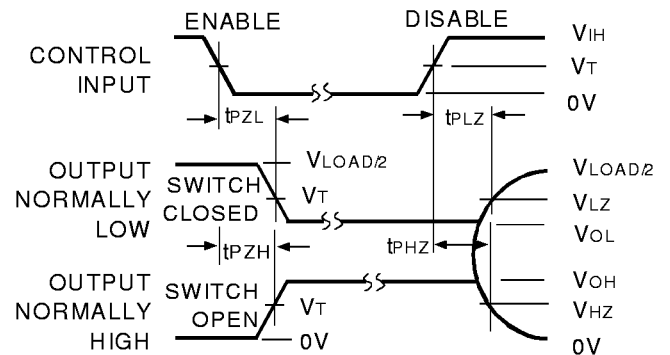
1. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.

PROPAGATION DELAY



4218 drw 06

ENABLE AND DISABLE TIMES



NOTE:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

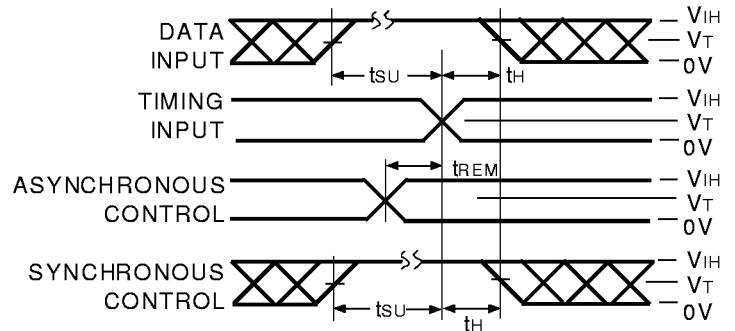
4218 drw 07

SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V _{LOAD}
Disable High Enable High	GND
All Other tests	Open

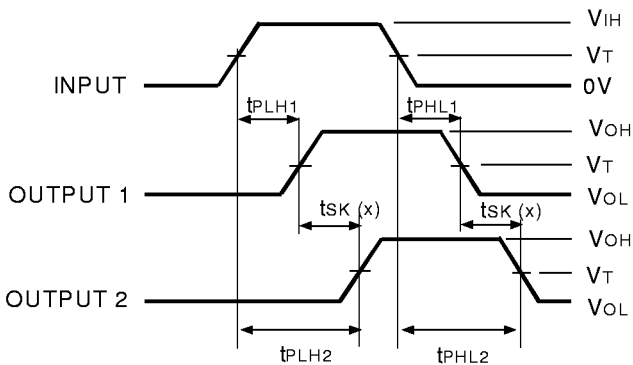
4218 Ink 13

SET-UP, HOLD AND RELEASE TIMES



4218 drw 08

OUTPUT SKEW - tSK (x)



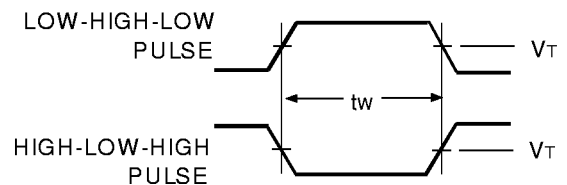
$$t_{SK}(x) = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

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NOTES:

- For t_{SK}(o) OUTPUT1 and OUTPUT2 are any two outputs.
- For t_{SK}(b) OUTPUT1 and OUTPUT2 are in the same bank.

PULSE WIDTH



4218 drw 09

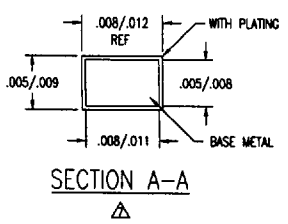
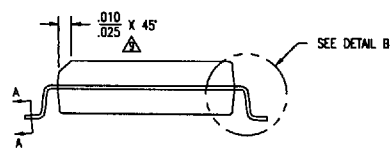
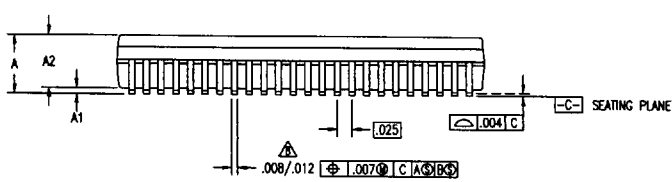
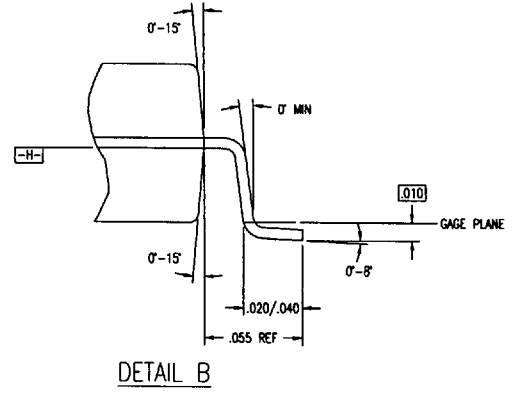
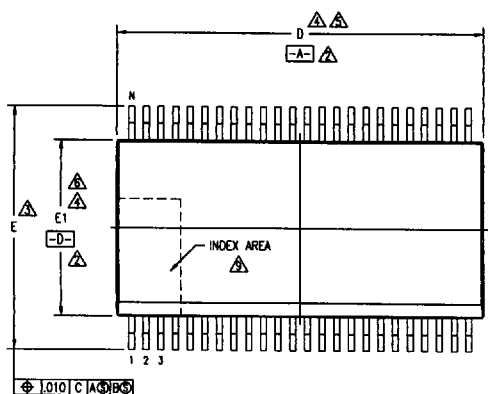
ORDERING INFORMATION

IDT	XX	ALVC	X	XX	XXX	XX	
Temp. Range	Bus-Hold	Family	Device Type	Package			
						PV	Shrink Small Outline Package (SO48-1)
						PA	Thin Shrink Small Outline Package (SO48-2)
						PF	Thin Very Small Outline Package (SO48-3)
					374		16-Bit Register
			16				Double-Density 3.3 Volt w/Resistors, ±24mA
			162				Double-Density 3.3 Volt w/Resistors, ±12mA
		Blank					No-Bus-hold
		H					Bus-hold
					74		-40 °C to +85 °C

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PACKAGE DIAGRAM OUTLINES
SSOP

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. WJ
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	



TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc. 2975 Slender Way, Santa Clara, CA 95054 PHONE: (408) 727-8118 FAX: (408) 462-8874 TWC: 910-338-2070	
DECIMAL	ANGULAR	DATE	TITLE
XXE	Z	08/15/90	PV PACKAGE OUTLINE
XXXZ			.300" BODY WIDTH SSOP
XXXXZ			.025" PITCH
APPROVALS	DATE	SIZE	DRAWING No.
DRWN: AA	08/15/90	C	PSC-4029
CHECKED			REV 02
DO NOT SCALE DRAWING			

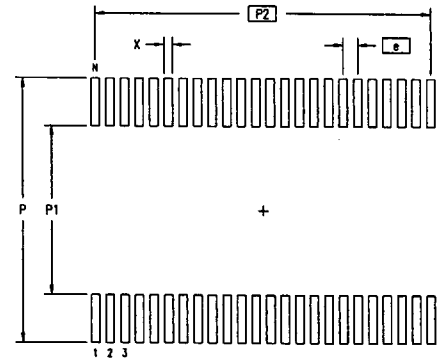
PACKAGE DIAGRAM OUTLINES

SSOP (Continued)

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. WU
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	

SYMBOL	DWG # S048-1				DWG # S056-1			
	JEDEC VARIATION			NOTE	JEDEC VARIATION			NOTE
	AA				AB			
	MIN	NOM	MAX		MIN	NOM	MAX	
A	.095	.102	.110		.095	.102	.110	
A1	.008	.012	.016		.008	.012	.016	
A2	.088	.090	.092		.088	.090	.092	
D	.620	.625	.630	4,5	.720	.725	.730	4,5
E	.395	.405	.420	3	.395	.405	.420	3
E1	.291	.295	.299	4,6	.291	.295	.299	4,6
N	48				56			

LAND PATTERN DIMENSIONS



	MIN	MAX	MIN	MAX
P	.450	.458	.450	.458
P1	.282	.290	.282	.290
P2	.575 BSC		.675 BSC	
X	.010	.018	.010	.018
e	.025 BSC		.025 BSC	
N	48		56	

NOTES:

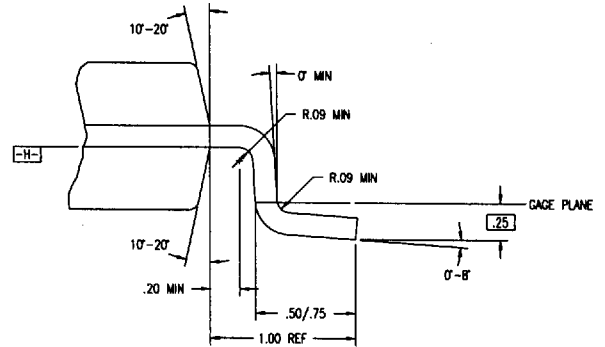
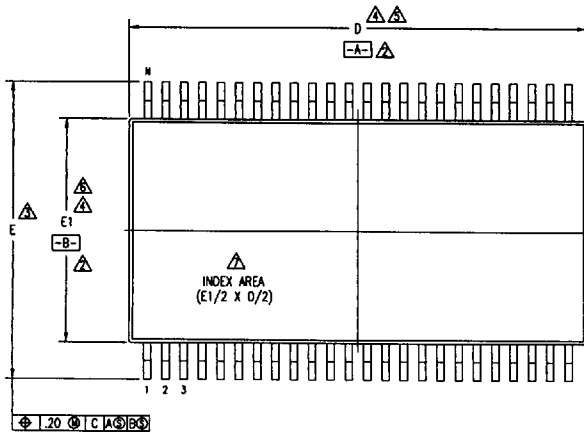
- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- ⚠ DATUMS [-A-] AND [-B-] TO BE DETERMINED AT DATUM PLANE [-H-]
- ⚠ DIMENSION E TO BE DETERMINED AT SEATING PLANE [-C-]
- ⚠ DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE [-H-]
- ⚠ DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 PER SIDE
- ⚠ DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .015 PER SIDE
- ⚠ THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND .010 FROM LEAD TIP
- ⚠ LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .004 IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- ⚠ THE CHAMFER ON THE PACKAGE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE ZONE INDICATED
- 10 ALL DIMENSIONS ARE IN INCHES
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-118, VARIATION AA & AB

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2975 Stander Way, Santa Clara, CA 95054	
X.XX ±	±	PHONE: (408) 727-8116	
X.XXX ±		FAX: (408) 482-8874 TWC: 810-338-2070	
APPROVALS DATE		TITLE	
DRAWN Ad	08/15/90	PV PACKAGE OUTLINE	
CHECKED		.300" BODY WIDTH SSOP	
		.025" PITCH	
SIZE	DRAWING No.	REV	
C	PSC-4029	02	
DO NOT SCALE DRAWING			

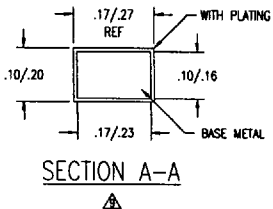
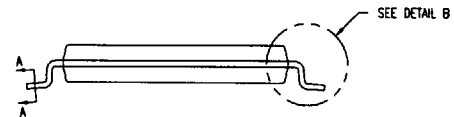
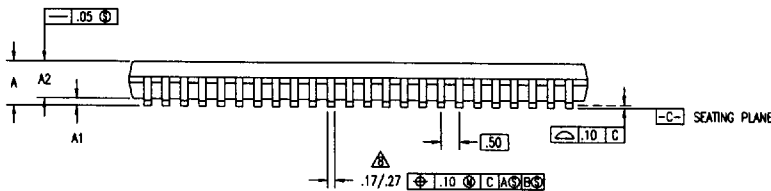
PACKAGE DIAGRAM OUTLINES

TSSOP

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VJ
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. VJ
27494	03	REDRAW TO JEDEC FORMAT	03/06/95	



DETAIL B



SECTION A-A

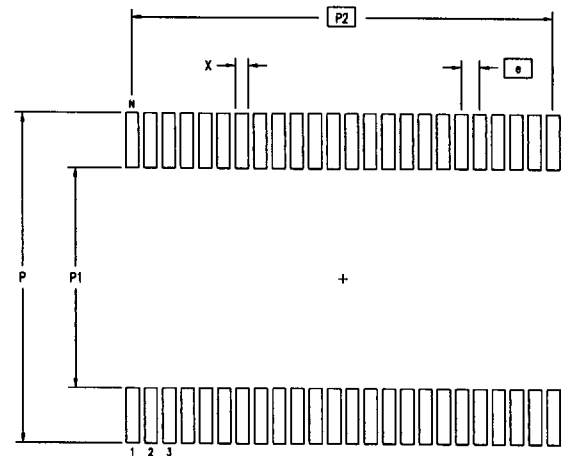
TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc. 2975 Slender Way, Santa Clara, CA 95054 PHONE: (408) 727-8118 FAX: (408) 492-8674 TWC: 910-338-2070
DECIMAL	ANGULAR	
$\pm .004$	$\pm .004$	
APPROVALS	DATE	TITLE
DRAWN	01/15/93	PA PACKAGE OUTLINE
CHECKED		6.10 mm BODY WIDTH TSSOP
		.50 mm PITCH
SIZE	DRAWING No.	REV
C	PSC-4039	03
DO NOT SCALE DRAWING		

PACKAGE DIAGRAM OUTLINES
TSSOP (Continued)

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. WU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. WU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	

SYMBOL	DWG # S048-2			NOTE	DWG # S056-2			NOTE		
	JEDEC VARIATION				JEDEC VARIATION					
	ED	EE			ED	EE				
MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX		
A	-	-	1.10	-	-	1.10	-	-	1.10	
A1	.05	-	.15	.05	-	.15	.05	-	.15	
A2	.85	1.00	1.05	.85	1.00	1.05	.85	1.00	1.05	
D	12.40	12.50	12.60	4,5	13.90	14.00	14.10	4,5		
E	7.95	8.10	8.25	3	7.95	8.10	8.25	3		
E1	6.00	6.10	6.20	4,6	6.00	6.10	6.20	4,6		
N	48				56					

LAND PATTERN DIMENSIONS



NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- △ DATUMS \square -A- AND \square -B- TO BE DETERMINED AT DATUM PLANE \square -H-
- △ DIMENSION E TO BE DETERMINED AT SEATING PLANE \square -C-
- △ DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE \square -H-
- △ DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
- △ DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE
- △ DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- △ LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- △ THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- 10 ALL DIMENSIONS ARE IN MILLIMETERS
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MQ-153, VARIATION ED & EE

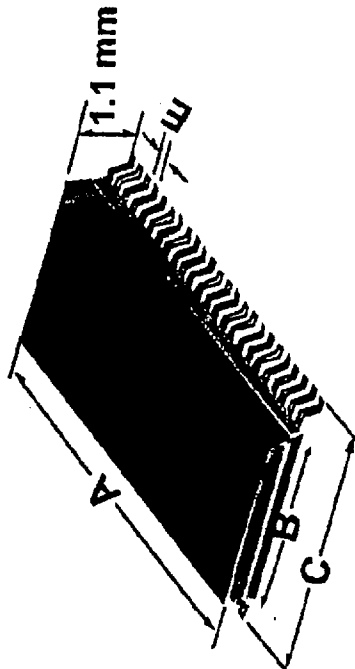
	MIN	MAX	MIN	MAX
P	8.90	9.10	8.90	9.10
P1	5.90	6.10	5.90	6.10
P2	11.50	BSC	13.50	BSC
X	.30	.40	.30	.40
e	.50	BSC	.50	BSC
N	48		56	

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2975 Slender Way, Santa Clara, CA 95054	
±	±	PHONE: (408) 727-8118	
±	±	FAK: (408) 482-8874	TWX: 910-338-2070
±	±		
APPROVALS	DATE	TITLE PA PACKAGE OUTLINE	
DRAWN	01/19/93	6.10 mm BODY WIDTH TSSOP	
CHECKED		.50 mm PITCH	
		SIZE C	DRAWING No. PSC-4039
			REV 03
DO NOT SCALE DRAWING			



TVSOP

The Most Compact Double Density Package

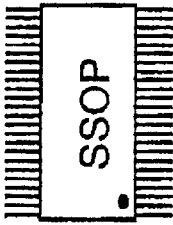


TVSOP Package	Typical Dimensions (in mm)				Area (mm ²)
	A	B	C	E	
48 Pin	9.80	4.40	6.40	0.40	63.00
56 Pin	11.30	4.40	6.40	0.40	72.30
80 Pin	17.00	6.10	8.10	0.40	137.80
100 Pin	20.80	6.10	8.10	0.40	168.50

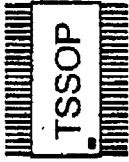


Double Density Packaging

48-Pin



16.0 x 10.3 x 2.6 mm
pin pitch = 0.635 mm
Area = 164.8 mm²

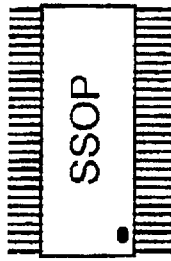


12.5 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 101.3 mm²



9.8 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 62.7 mm²

56-Pin



18.4 x 10.3 x 2.6 mm
pin-pitch = 0.635 mm
Area = 189.5 mm²



14.0 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 113.4 mm²



11.3 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 72.3 mm²

TVSOP	Area (mm ²)	%Smaller Than SSOP	%Smaller Than TSSOP
48 pin	63.00	61.9	38.0
56 pin	72.30	62.2	36.0